ABSTRACT

Method for manufacturing a bump on a terminal face (21) of a semiconductor substrate (20), in which the terminal face is nucleated to generate a basic metallization through electrolytic coating of the terminal face with zincate, in such a way that zinc particles (24) electrolytically deposited on the terminal face serve as nuclei for an ensuing contact metallization (28) autocatalytically deposited on the basic metallization, wherein, in addition to the electrolytic coating with zincate, an electrolytic coating of the terminal face with palladium takes place, in such a way that, in addition to zinc particles (24), palladium particles (25) deposited on the terminal face serve as nuclei for the contact metallization subsequently autocatalytically deposited on the terminal face.

(Fig. 4)